

RMF500 Technical Specifications

PRINTER	RMF500	
CONSTRUCTION	Build Volume (W × D × H)	
	Single Extruder Print	Dual Extruder Print
	500 × 500 × 500 mm	500 × 500 × 500 mm
	Machine Size (W × D × H)	
	1340 × 990 × 2370 mm	
ELECTRICAL	Power Supply Input	30 A @ 3-Phase 380 V AC
	Power Supply Output	24 V, 350 W; 12 V, 75 W;
GENERAL	Print Technology	FFF
	Print Head	Independent Dual Electric Nozzle Extrusion System
	Filament Diameter	1.75 mm
	XYZ Positioning Resolution	1, 1, 0.09765 micron
	Print Head Travel Speed	≤ 300 mm/s
	Build Plate	PEI Build Plate with Vacuum Manifold
	Max Build Plate Temperature	110°C
	Heated Bed Material	Steel
	Build Plate Leveling	Auto leveling
	Supported Materials	Raise3D Industrial PA12 CF, Raise3D Industrial PA12 CF Support (PPA CF, PPS CF, PET CF and PPA GF Coming soon)
	Layer Height	0.05-0.75 mm
	Nozzle Diameter	0.6 mm (Default), 0.8 mm (Coming soon)
	Max Nozzle Temperature	330°C
	Connectivity	Wi-Fi, LAN, USB port, Live camera
	Operating Ambient Temperature	13-39°C, 30-70% RH Non-Condensing (HOLD)
	Storage Temperature	-40°C to +54°C, 10-85% RH Non-Condensing (HOLD)
SOFTWARE	Slicing Software	ideaMaker
	Supported File Types	STL/ OBJ/ 3MF/ OLTP
	Supported OS	Windows/ macOS/ Linux
	Machine Code Type	GCODE
PRINTER CONTROLLER	User Interface	13.3-inch Touchscreen
	Network	Ethernet, Wireless 802.11 b/g/n, Dual Mode Wi-Fi
	Screen Resolution	1920 × 1080
	Motion Controller	Rockchip ARM Cortex-M4
	Logic Controller	Rockchip RK3399 ARM Dual Cortex-A72 and Quad Cortex-A53 1.8 GHz
	Memory	1 GB
	Onboard Flash	8 GB
	OS	Embedded Linux
	Ports	USB 2.0 × 1